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Customer No.: 31561
Docket No.: 13184-US-PA
Application No.: 10/710,696

REMARKS

Present Status of the Application

Claims 1-9 are rejected under 35 U.S.C. 112, second paragraph. Claims 10-14 and 17-21 are rejected under 35 U.S.C. 103(a) as being unpatentable over Mund et al. (U.S. Pub. 2006/0030074; hereinafter Mund) in view of Noma et al. (U. S. Pub. 2004/0137723; hereinafter Nima). Applicants have amended independent claims 1 and 10. After entry of amendments, claims 1-14 and 17-21 remain pending in the present application, and reconsideration of those claims is respectfully requested.

About Amendments

Applicants have amended independent claims 1 and 10 to improve clarity. The feature of glue with the spacers therein has been recited. Therefore, the glue fully surrounds the spacers. After the dielectric substrate is disposed over the wafer, due to the intrinsic fluidity of the glue, the spacers would contact the dielectric substrate and the wafer at both sides while the side surface portion is surrounded by the glue. It is believed that the amendment has clearly recited the features such as FIG. 1C and precluded the glue 314 of Mund, in which the glue 314 only between the spacer 310 and the substrate 312 and the spacer does not contact the substrate 312.

Discussion of Claim Rejections under 35 USC 112

Claims 1-9 are rejected under 35 U.S.C. 112, second paragraph.

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Applicants have amended claim 1 to improve the clarity, and therefore overcome the rejections. Claim 10 has been also amended.

Discussion of Claim Rejections under 35 USC 103

Claims 10-14 and 17-21 are rejected under 35 U.S.C. 103(a) as being unpatentable over Mund in view of Noma. Applicants respectfully traverse the rejections for at least the reasons set forth below.

1. As stated in previous Response, as recited in claim 10, the spacers 130 in FIG. 1C are surrounded by the glue, except the portion being contact the substrate and the wafer, to hold the substrate 140 before the substrate 140 is ground. The spacers inside the glue can contact between the wafer and the dielectric substrate to provide a constant gap. Here, due to fluidity of the glue, after the dielectric substrate is disposed over the wafer, the spacers can contact the substrate and the wafer at both sides to hold the constant gap. Due to the holding effect by the spacers 130, the substrate 140 is ground without damaging the device 114.

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2. In re Mund (Fig. 9), the bonding frame 310 is considered as the spacer of the present invention and the bonding locations 314 is considered as the glue of the present invention by the Office Action. In this manner, the glue 314 does not contain the spacer 310 in Mund. In further, the glue 314 only between the spacer 310 and the substrate 312 and the spacer 310 does not contact the substrate 312.

3. In re Noma, Noma does not further provide the missing features in Mund, as discussed above. The features recited independent claim 10 are not fully disclosed.

For at least the foregoing reasons, Applicants respectfully submit that independent claims 1 and 10 patently define over the prior art references, and should be allowed. For at least the same reasons, dependent claims 2-9, 11-14 and 17-21 patently define over the prior art references as well.

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CONCLUSION

For at least the foregoing reasons, it is believed that all the pending claims 1-14 and 17-21 of the invention patently define over the prior art and are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Respectfully submitted,

Date :

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